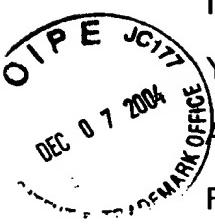


**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**



In re Patent Application of ) **MAIL STOP AMENDMENT**  
Yoshihisa SATOH et al. )  
Application No.: 09/720,676 )  
Filed: December 29, 2000 )  
For: SYNTHETIC RESIN MOLDING, )  
MOLD APPARATUS FOR AND )  
METHOD OF ADJUSTING A )  
TEMPERTURE OF THE MOLD )

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated September 9, 2004, please amend the above-identified patent application as follows:

12/08/2004 HDEMESS1 00000106 09720676  
01 FC:1201 176.00 OP